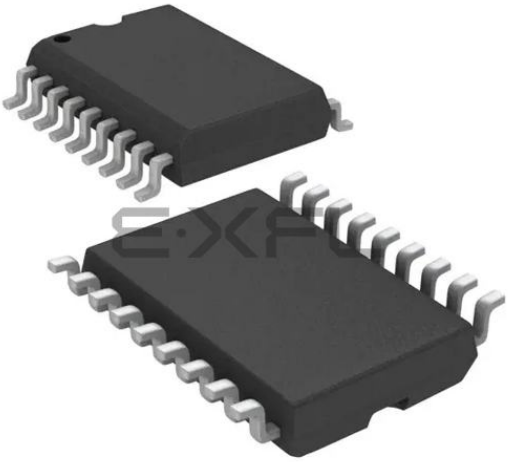

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce625t-20i-so

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TABLE 1-1: PIC16CE62X FAMILY OF DEVICES

		PIC16CE623	PIC16CE624	PIC16CE625
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
	Data Memory (bytes)	96	96	128
Peripherals	EEPROM Data Memory (bytes)	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.
All PIC16CE62X Family devices use serial programming with clock pin RB6 and data pin RB7.

4.2 Data Memory Organization

The data memory (Figure 4-4 and Figure 4-5) is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each Bank. Register locations 20-7Fh (Bank0) on the PIC16CE623/624 and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16CE625 are General Purpose Registers implemented as static RAM. Some special purpose registers are mapped in Bank 1. In all three microcontrollers, address space F0h-FFh (Bank1) is mapped to 70-7Fh (Bank0) as common RAM.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 96 x 8 in the PIC16CE623/624 and 128 x 8 in the PIC16CE625. Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

FIGURE 4-4: DATA MEMORY MAP FOR THE PIC16CE623/624

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h		EEINTF	90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h–7Fh	General Purpose Register		A0h–EFh
		Accesses 70h-7Fh	F0h–FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

FIGURE 4-5: DATA MEMORY MAP FOR THE PIC16CE625

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h		EEINTF	90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h–7Fh	General Purpose Register	General Purpose Register	A0h–BFh
			C0h–EFh
		Accesses 70h-7Fh	F0h–FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

6.1 Bus Characteristics

In this section, the term “processor” refers to the portion of the PIC16CE62X that interfaces to the EEPROM through software manipulating the EEINTF register. The following **bus protocol** is to be used with the EEPROM data memory.

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is HIGH will be interpreted by the EEPROM as a START or STOP condition.

Accordingly, the following bus conditions have been defined (Figure 6-1).

6.1.1 BUS NOT BUSY (A)

Both data and clock lines remain HIGH.

6.1.2 START DATA TRANSFER (B)

A HIGH to LOW transition of the SDA line while the clock (SCL) is HIGH determines a START condition. All commands must be preceded by a START condition.

6.1.3 STOP DATA TRANSFER (C)

A LOW to HIGH transition of the SDA line while the clock (SCL) is HIGH determines a STOP condition. All operations must be ended with a STOP condition.

6.1.4 DATA VALID (D)

The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the HIGH period of the clock signal.

The data on the line must be changed during the LOW period of the clock signal. There is one bit of data per clock pulse.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of the data bytes transferred between the START and STOP conditions is determined by the processor and is theoretically unlimited, although only the last sixteen will be stored when doing a write operation. When an overwrite does occur, it will replace data in a first-in, first-out fashion.

6.1.5 ACKNOWLEDGE

The EEPROM will generate an acknowledge after the reception of each byte. The processor must generate an extra clock pulse which is associated with this acknowledge bit.

Note:	Acknowledge bits are not generated if an internal programming cycle is in progress.

When the EEPROM acknowledges, it pulls down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. The processor must signal an end of data to the EEPROM by not generating an acknowledge bit on the last byte that has been clocked out of the EEPROM. In this case, the EEPROM must leave the data line HIGH to enable the processor to generate the STOP condition (Figure 6-2).

FIGURE 6-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

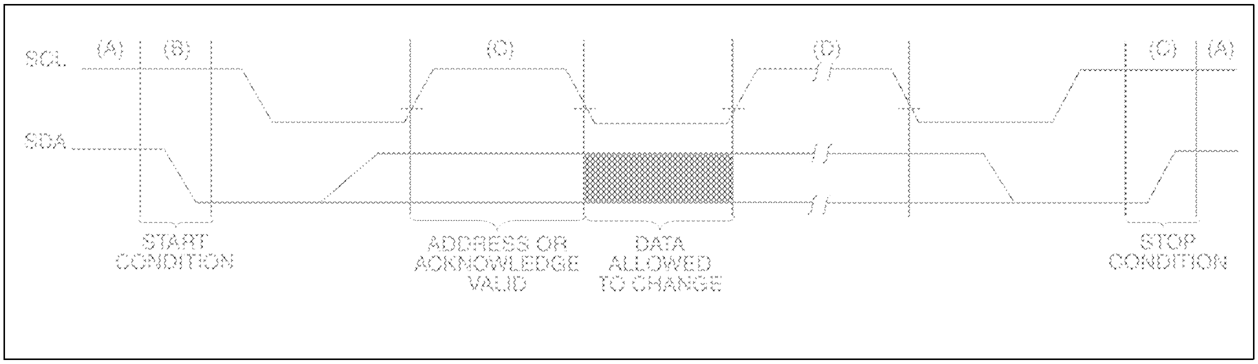
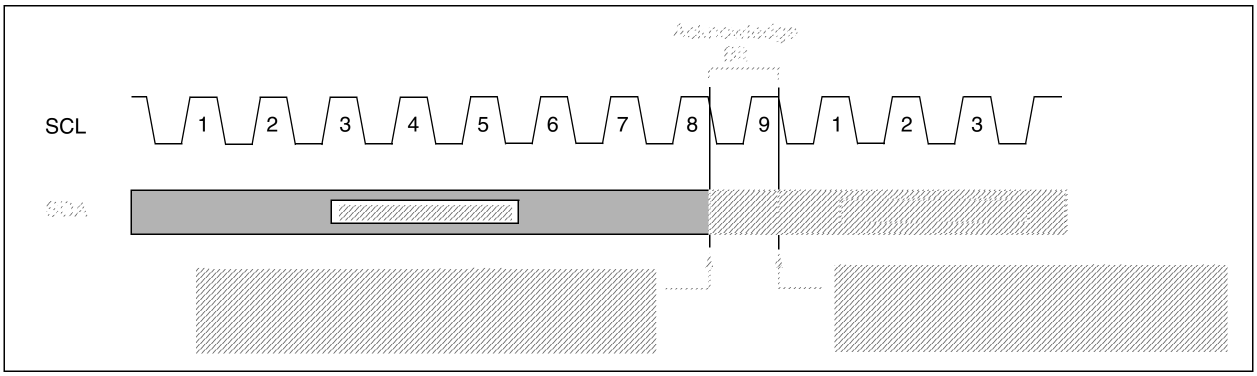


FIGURE 6-2: ACKNOWLEDGE TIMING

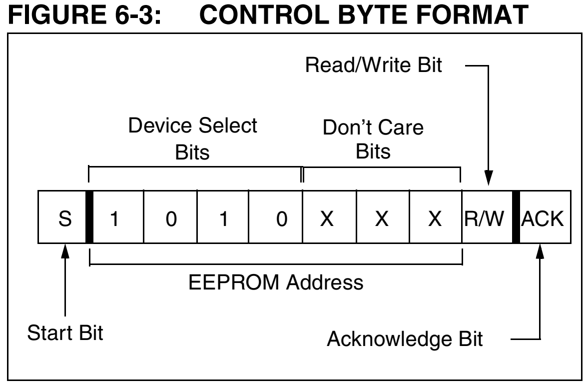


6.2 Device Addressing

After generating a START condition, the processor transmits a control byte consisting of a EEPROM address and a Read/$\overline{\text{Write}}$ bit that indicates what type of operation is to be performed. The EEPROM address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one, a read operation is selected, and when set to a zero, a write operation is selected. (Figure 6-3). The bus is monitored for its corresponding EEPROM address all the time. It generates an acknowledge bit if the EEPROM address was true and it is not in a programming mode.

FIGURE 6-3: CONTROL BYTE FORMAT



7.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to TMR0.

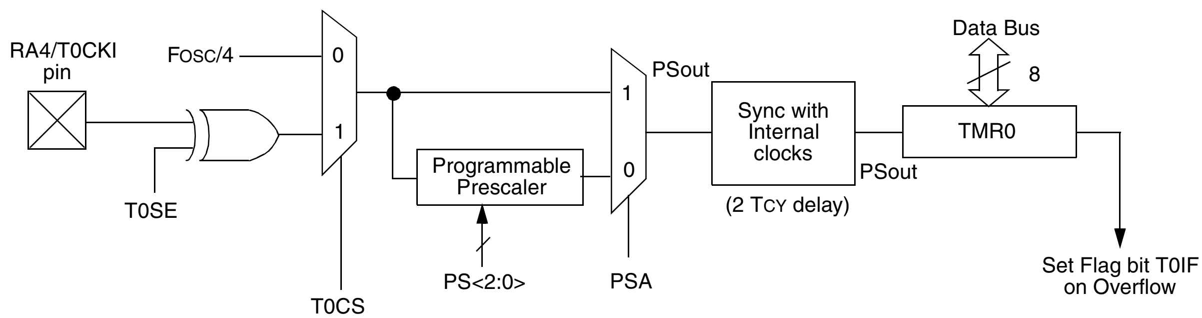
Counter mode is selected by setting the T0CS bit. In this mode Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

7.1 Timer0 Interrupt

Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. See Figure 7-4 for Timer0 interrupt timing.

FIGURE 7-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0SE, T0CS, PS2, PS1, PS0 and PSA are located in the OPTION register.
2: The prescaler is shared with Watchdog Timer (Figure 7-6)

FIGURE 7-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER

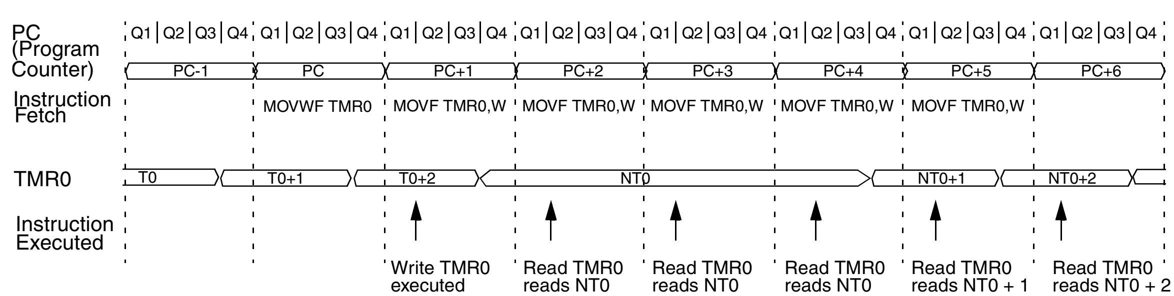


FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

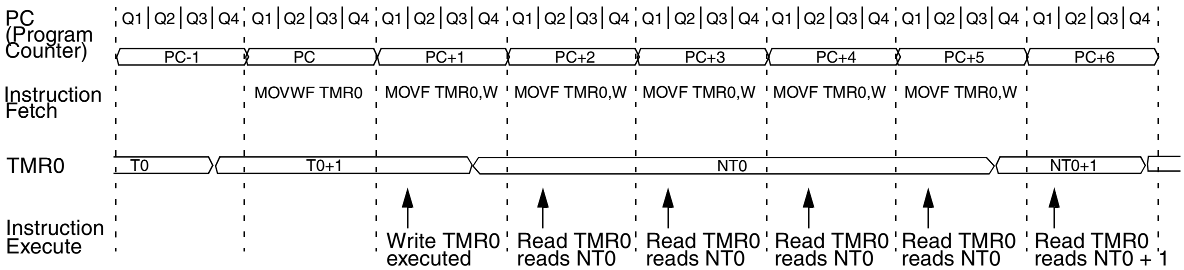
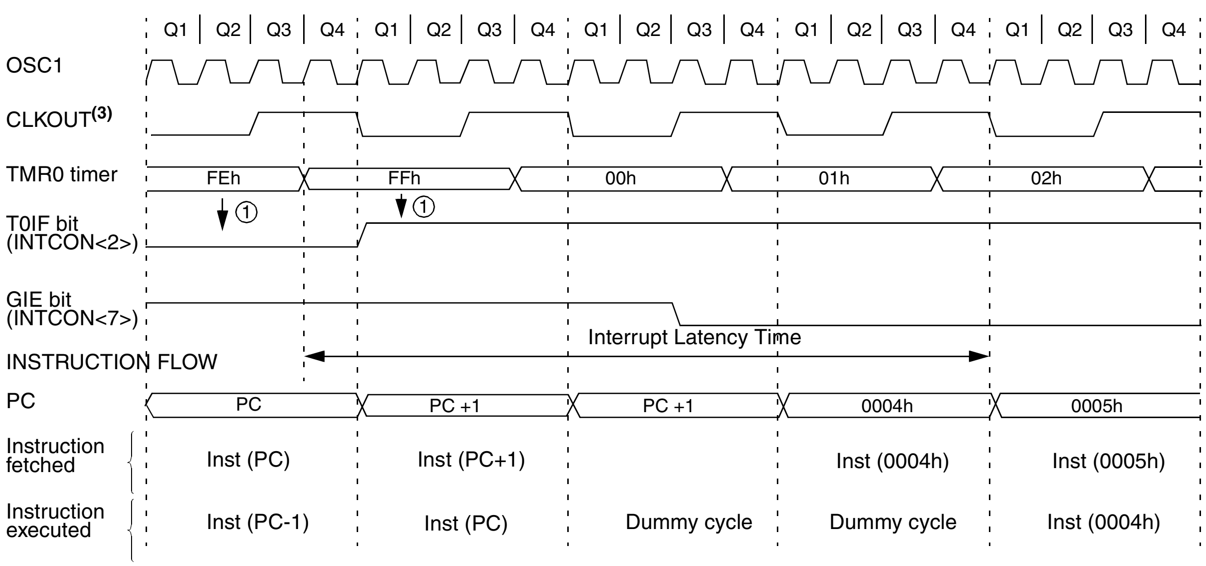


FIGURE 7-4: TIMER0 INTERRUPT TIMING



Note 1: T0IF interrupt flag is sampled here (every Q1).
2: Interrupt latency = 3TCY, where TCY = instruction cycle time.
3: CLKOUT is available only in RC oscillator mode.

7.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

7.2.1 EXTERNAL CLOCK SYNCHRONIZATION

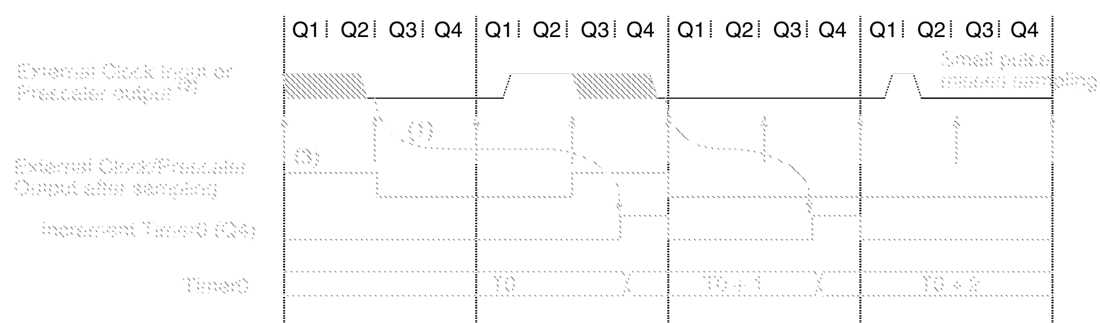
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

7.2.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 7-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 7-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.
2: External clock if no prescaler selected; prescaler output otherwise.
3: The arrows indicate the points in time where sampling occurs.

The code example in Example 8-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

EXAMPLE 8-1: INITIALIZING COMPARATOR MODULE

```
FLAG_REG EQU        0X20
CLRF     FLAG_REG   ;Init flag register
CLRF     PORTA      ;Init PORTA
MOVF     CMCON,W    ;Move comparator contents to W
ANDLW    0xC0       ;Mask comparator bits
IORWF    FLAG_REG,F ;Store bits in flag register
MOVLW    0x03       ;Init comparator mode
MOVWF    CMCON      ;CM<2:0> = 011
BSF      STATUS,RP0 ;Select Bank1
MOVLW    0x07       ;Initialize data direction
MOVWF    TRISA      ;Set RA<2:0> as inputs
                    ;RA<4:3> as outputs
                    ;TRISA<7:5> always read '0'
BCF      STATUS,RP0 ;Select Bank 0
CALL     DELAY 10   ;10µs delay
MOVF     CMCON,F    ;Read CMCON to end change condition
BCF      PIR1,CMIF  ;Clear pending interrupts
BSF      STATUS,RP0 ;Select Bank 1
BSF      PIE1,CMIE  ;Enable comparator interrupts
BCF      STATUS,RP0 ;Select Bank 0
BSF      INTCON,PEIE ;Enable peripheral interrupts
BSF      INTCON,GIE ;Global interrupt enable
```

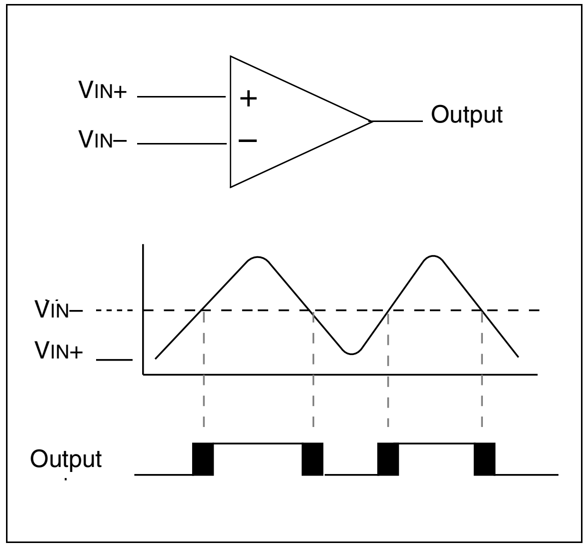
8.2 Comparator Operation

A single comparator is shown in Figure 8-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN–, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN–, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 8-2 represent the uncertainty due to input offsets and response time.

8.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator operating mode. The analog signal that is present at VIN– is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 8-2).

FIGURE 8-2: SINGLE COMPARATOR



8.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD and can be applied to either pin of the comparator(s).

8.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 13, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 8-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

EXAMPLE 9-1: VOLTAGE REFERENCE CONFIGURATION

```
MOVLW    0x02         ; 4 Inputs Muxed
MOVWF    CMCON        ; to 2 comps.
BSF      STATUS,RP0   ; go to Bank 1
MOVLW    0x07         ; RA3-RA0 are
MOVWF    TRISA        ; outputs
MOVLW    0xA6         ; enable VREF
MOVWF    VRCON        ; low range
                      ; set VR<3:0>=6
BCF      STATUS,RP0   ; go to Bank 0
CALL     DELAY10      ; 10µs delay
```

9.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 9-1) keep VREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The absolute accuracy of the Voltage Reference can be found in Table 13-2.

9.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

9.4 Effects of a Reset

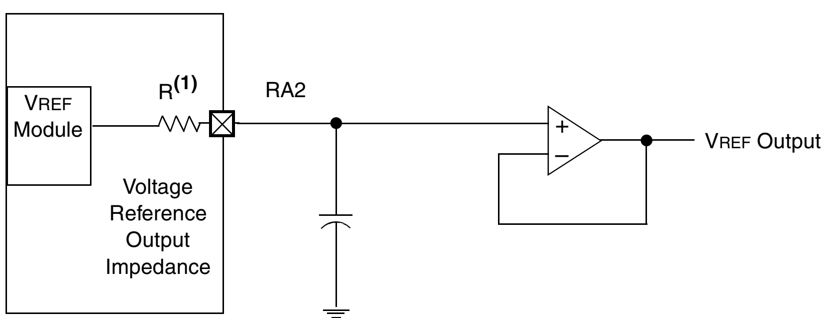
A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

9.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 9-2 shows an example buffering technique.

FIGURE 9-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



Note 1: R is dependent upon the Voltage Reference Configuration VRCON<3:0> and VRCON<5>.

TABLE 9-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR / BOD	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: - = Unimplemented, read as "0"

BCF — Bit Clear f

Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$0 \rightarrow$ (f<b>)
Status Affected:	None
Encoding:	`01` | `00bb` | `bfff` | `ffff`
Description:	Bit 'b' in register 'f' is cleared.
Words:	1
Cycles:	1
Example	`BCF FLAG_REG, 7` Before Instruction FLAG_REG = 0xC7 After Instruction FLAG_REG = 0x47

BSF — Bit Set f

Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$1 \rightarrow$ (f<b>)
Status Affected:	None
Encoding:	`01` | `01bb` | `bfff` | `ffff`
Description:	Bit 'b' in register 'f' is set.
Words:	1
Cycles:	1
Example	`BSF FLAG_REG, 7` Before Instruction FLAG_REG = 0x0A After Instruction FLAG_REG = 0x8A

BTFSC — Bit Test, Skip if Clear

Syntax:	[*label*] BTFSC f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	skip if (f<b>) = 0
Status Affected:	None
Encoding:	`01` | `10bb` | `bfff` | `ffff`
Description:	If bit 'b' in register 'f' is '0', then the next instruction is skipped. If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a two-cycle instruction.
Words:	1
Cycles:	1(2)

Example

```
HERE   BTFSC  FLAG,1
FALSE  GOTO   PROCESS_CODE
TRUE   •
       •
       •
```

Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `TRUE`
if FLAG<1>=1,
PC = address `FALSE`

RETURN — Return from Subroutine

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC

Status Affected: None

Encoding:

00	0000	0000	1000

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two cycle instruction.

Words: 1

Cycles: 2

Example: `RETURN`

After Interrupt
PC = TOS

RLF — Rotate Left f through Carry

Syntax: [*label*] RLF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

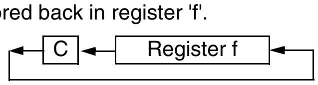
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example: `RLF REG1,0`

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

RRF — Rotate Right f through Carry

Syntax: [*label*] RRF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

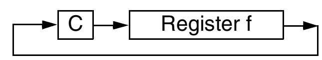
Operation: See description below

Status Affected: C

Encoding:

00	1100	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example: `RRF REG1,0`

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 0111 0011
C = 0

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into `SLEEP` mode with the oscillator stopped. See Section 10.8 for more details.

Words: 1

Cycles: 1

Example: `SLEEP`

SWAPF — Swap Nibbles in f

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>),
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

00	1110	dfff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.

Words: 1

Cycles: 1

Example

```
SWAPF REG,   0
```

Before Instruction

REG1 = 0xA5

After Instruction

REG1 = 0xA5
W = 0x5A

TRIS — Load TRIS Register

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

00	0000	0110	0fff

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC® MCU products, do not use this instruction.

XORLW — Exclusive OR Literal with W

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:

```
XORLW   0xAF
```

Before Instruction

W = 0xB5

After Instruction

W = 0x1A

XORWF — Exclusive OR W with f

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

00	0110	dfff	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example

```
XORWF    REG  1
```

Before Instruction

REG = 0xAF
W = 0xB5

After Instruction

REG = 0x1A
W = 0xB5

stand-alone mode the PRO MATE II can read, verify or program PIC devices. It can also set code-protect bits in this mode.

12.11 PICSTART Plus Entry Level Development System

The PICSTART programmer is an easy-to-use, low-cost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

PICSTART Plus supports all PIC devices with up to 40 pins. Larger pin count devices such as the PIC16C92X, and PIC17C76X may be supported with an adapter socket. PICSTART Plus is CE compliant.

12.12 SIMICE Entry-Level Hardware Simulator

SIMICE is an entry-level hardware development system designed to operate in a PC-based environment with Microchip's simulator MPLAB-SIM. Both SIMICE and MPLAB-SIM run under Microchip Technology's MPLAB Integrated Development Environment (IDE) software. Specifically, SIMICE provides hardware simulation for Microchip's PIC12C5XX, PIC12CE5XX, and PIC16C5X families of PIC 8-bit microcontrollers. SIMICE works in conjunction with MPLAB-SIM to provide non-real-time I/O port emulation. SIMICE enables a developer to run simulator code for driving the target system. In addition, the target system can provide input to the simulator code. This capability allows for simple and interactive debugging without having to manually generate MPLAB-SIM stimulus files. SIMICE is a valuable debugging tool for entry-level system development.

12.13 PICDEM-1 Low-Cost PIC MCU Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the MPLAB-ICE emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

12.14 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I^2C bus and separate headers for connection to an LCD module and a keypad.

12.15 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

12.16 PICDEM-17

The PICDEM-17 is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756, PIC17C762, and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included, and the user may erase it and program it with the other sample programs using the PRO MATE II or PICSTART Plus device programmers and easily debug

NOTES:

13.1 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2, 4)	–	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			–	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT osc mode, (Note 4)
			–	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS osc mode, (Note 6)
			–	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS osc mode
			–	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS osc mode
			–	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	–	–	2.2	μA	VDD = 3.0V
			–	–	5.0	μA	VDD = 4.5V*
			–	–	9.0	μA	VDD = 5.5V
			–	–	15	μA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	–	6.0	10	μA	VDD = 4.0V
					12	μA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	–	75	125	μA	$\overline{\text{BOD}}$ enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	–	30	60	μA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	–	80	135	μA	VDD = 4.0V
	ΔIEE Write	Operating Current	–		3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	–		1	mA	
	ΔIEE	Standby Current	–		30	μA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	–		100	μA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	–	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	–	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	–	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	–	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

13.3 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended) PIC16LCE62X (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature –40°C ≤ T_A ≤ +85°C for industrial and 0°C ≤ T_A ≤ +70°C for commercial and –40°C ≤ T_A ≤ +125°C for extended Operating voltage V_{DD} range as described in DC spec Table 13-1				
Parm No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Unit**	**Conditions**
	V_{IL}	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	V_{SS}	–	0.8V 0.15V_{DD}	V	V_{DD} = 4.5V to 5.5V, Otherwise
D031		with Schmitt Trigger input	V_{SS}		0.2V_{DD}	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in RC mode)	V_{SS}	–	0.2V_{DD}	V	Note1
D033		OSC1 (in XT and HS)	V_{SS}	–	0.3V_{DD}	V	
		OSC1 (in LP)	V_{SS}	–	0.6V_{DD} - 1.0	V	
	V_{IH}	**Input High Voltage**					
		I/O ports					
D040		with TTL buffer	2.0V .25V_{DD} + 0.8V	–	V_{DD} V_{DD}	V	V_{DD} = 4.5V to 5.5V, Otherwise
D041		with Schmitt Trigger input	0.8V_{DD}		V_{DD}		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8V_{DD}	–	V_{DD}	V	
D043		OSC1 (XT, HS and LP)	0.7V_{DD}	–	V_{DD}	V	
D043A		OSC1 (in RC mode)	0.9V_{DD}				Note1
D070	I_{PURB}	PORTB weak pull-up current	50	200	400	μA	V_{DD} = 5.0V, V_{PIN} = V_{SS}
	I_{IL}	**Input Leakage Current** (Notes 2, 3)					
		I/O ports (Except PORTA)			±1.0	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, pin at hi-impedance
D060		PORTA	–	–	±0.5	μA	Vss ≤ V_{PIN} ≤ V_{DD}, pin at hi-impedance
D061		RA4/T0CKI	–	–	±1.0	μA	Vss ≤ V_{PIN} ≤ V_{DD}
D063		OSC1, $\overline{MCLR}$	–	–	±5.0	μA	Vss ≤ V_{PIN} ≤ V_{DD}, XT, HS and LP osc configuration
	V_{OL}	**Output Low Voltage**					
D080		I/O ports	–	–	0.6	V	I_{OL}=8.5 mA, V_{DD}=4.5V, -40° to +85°C
			–	–	0.6	V	I_{OL}=7.0 mA, V_{DD}=4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	–	–	0.6	V	I_{OL}=1.6 mA, V_{DD}=4.5V, -40° to +85°C
			–	–	0.6	V	I_{OL}=1.2 mA, V_{DD}=4.5V, +125°C
	V_{OH}	**Output High Voltage** (Note 3)					
D090		I/O ports (Except RA4)	V_{DD}-0.7	–	–	V	I_{OH}=-3.0 mA, V_{DD}=4.5V, -40° to +85°C
			V_{DD}-0.7	–	–	V	I_{OH}=-2.5 mA, V_{DD}=4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	V_{DD}-0.7	–	–	V	I_{OH}=-1.3 mA, V_{DD}=4.5V, -40° to +85°C
			V_{DD}-0.7	–	–	V	I_{OH}=-1.0 mA, V_{DD}=4.5V, +125°C
*D150	V_{OD}	**Open-Drain High Voltage**			8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	COSC 2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	Cio	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

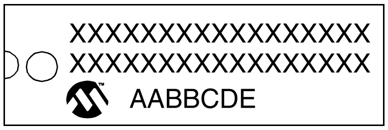
Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16CE62X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

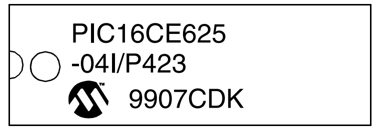
3: Negative current is defined as coming out of the pin.

14.1 Package Marking Information

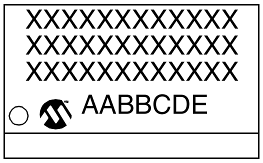
18-Lead PDIP



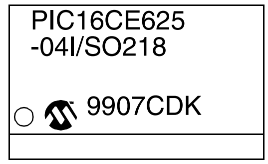
Example



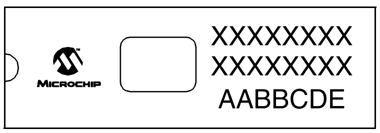
18-Lead SOIC (.300")



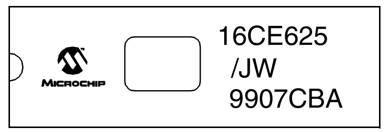
Example



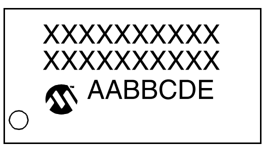
18-Lead CERDIP Windowed



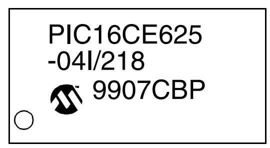
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

NOTES: